



Smart Computing and Big Data Analysis: Latest Advances and Applications

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Message from the Guest Editors

Dear Colleagues,

Smart computing and big data have become recently essential keywords for driving new technologies and innovative solutions in many applications. Big data analysis is a variety of advanced techniques which draws hidden rules, patterns, and knowledge from very large, diverse data to provide valuable insights and improvements in business, manufacturing, healthcare, etc. Smart computing is also a hot topic which combines advanced computer technologies to create new systems, applications, and services in diverse application such as business, health-care, industrial systems, and so on.

We invite the academic community and relevant industrial partners to submit papers to this Special Issue, on research results, application developments, and practical experiences in relevant fields and topics including (but not limited to) the following:

Novel techniques for big data and smart computing; Tools and systems for big data and smart computing; Machine learning for big data; Infrastructure and platform for smart computing; Big data analytics and social media; Cloud and grid computing; Mobile communications and networks; Application of big data and smart computing

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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